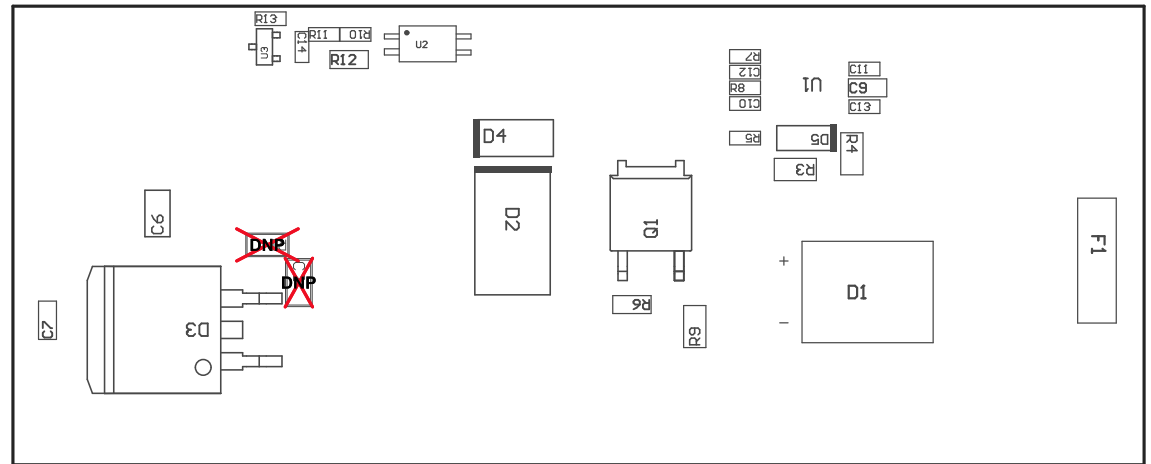


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20809	REV: A	SVN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/27/2017	2:55:16 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20809	REV: A	SVN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/27/2017 2:55:17 PM		TEXAS INSTRUMENTS

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